KURODA

High Precision Wafer Flatness Measurement Machine

Nanometro 300TT

黒田精工株式会社

nanometro®

KURODA

nanometro *TT* series

KURODA introduces following in-line inspection system

For 200mm wafer 200TT

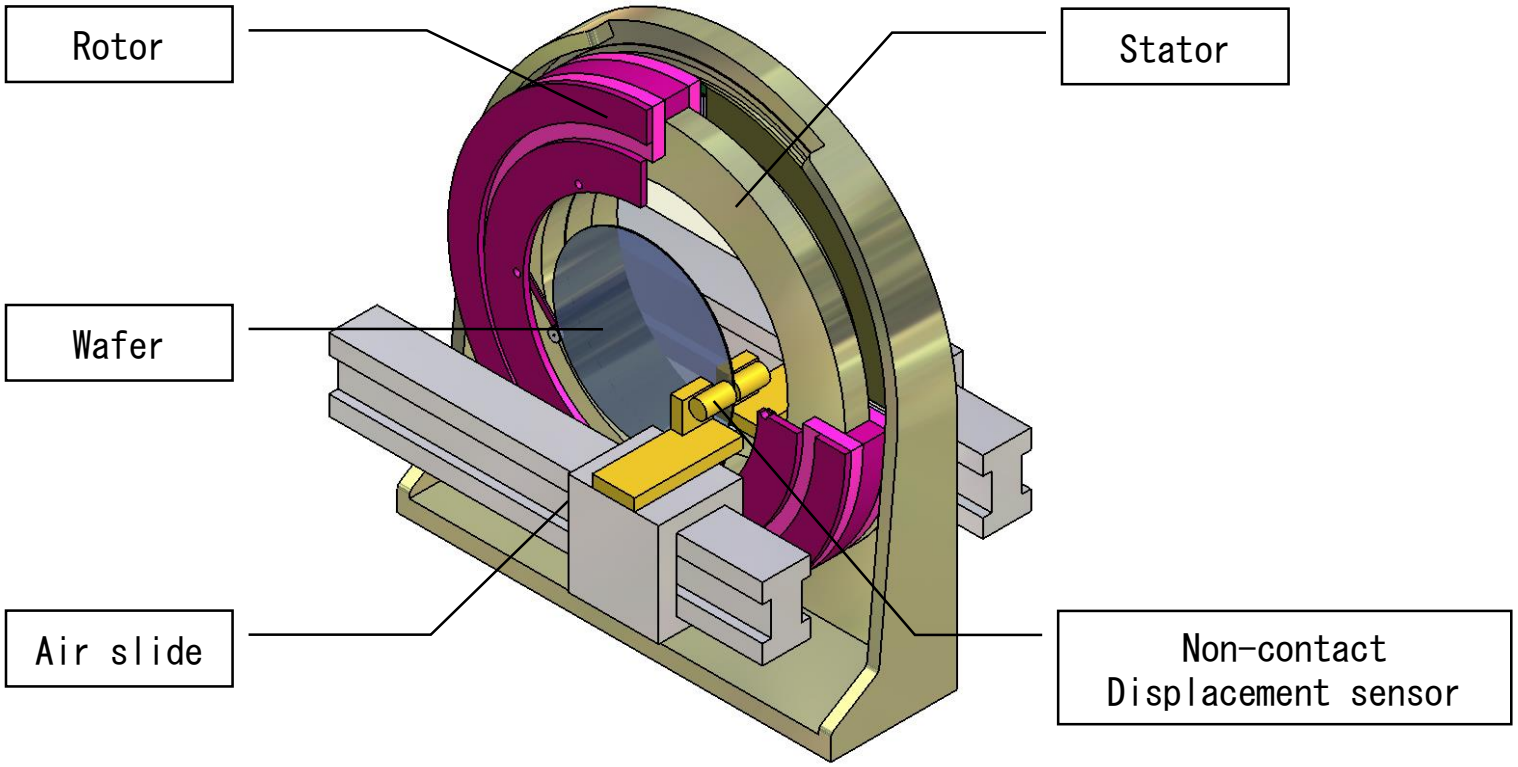
For 300mm wafer 300TT

nanometro® 300TT/200TT

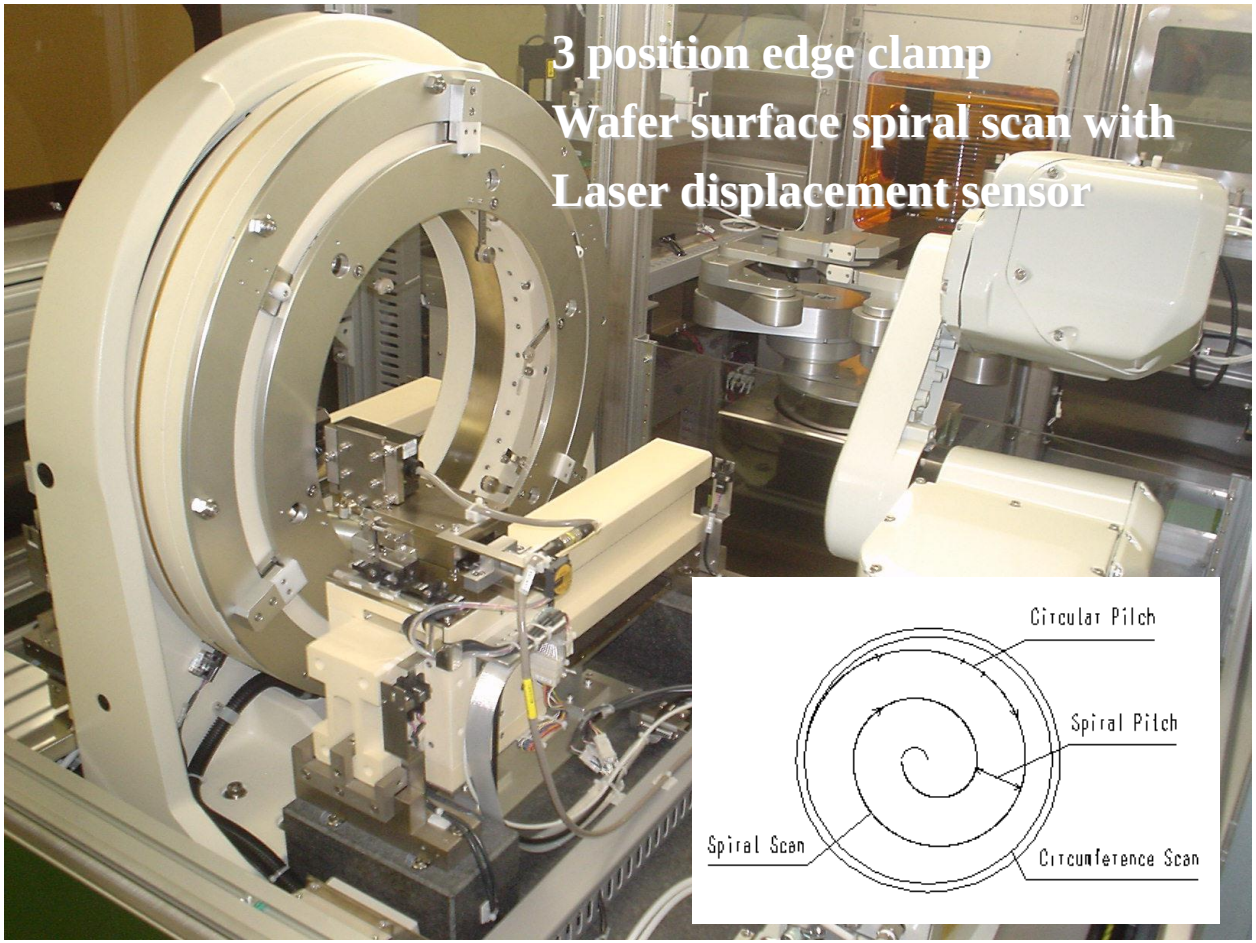
Characteristics of 300 TT

- High movement precision
- Edge exclusion Min. 1mm
- Conformable to on-line requirement
- FOUP. FOSB
- Various measurement modes
  - Ⅰ Flatness, SORI measurement
  - Ⅱ Radial measurement
  - Ⅲ Edge area measurement

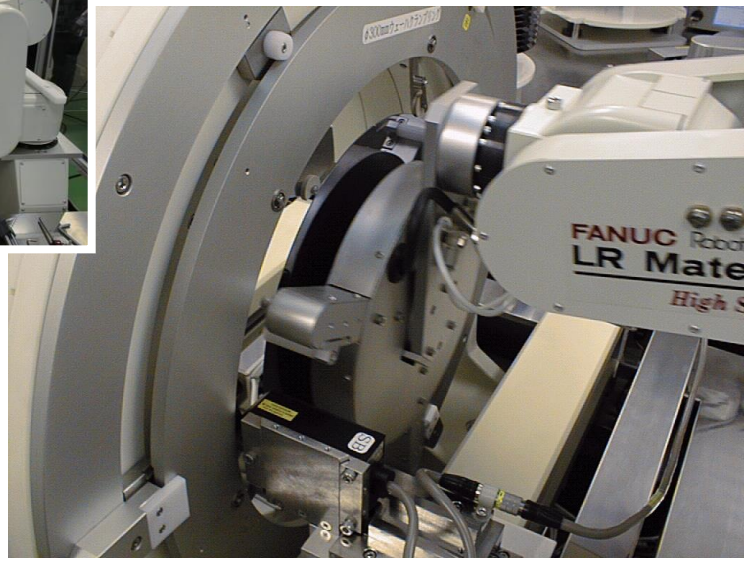
Construction of 300TT



Construction of 300TT

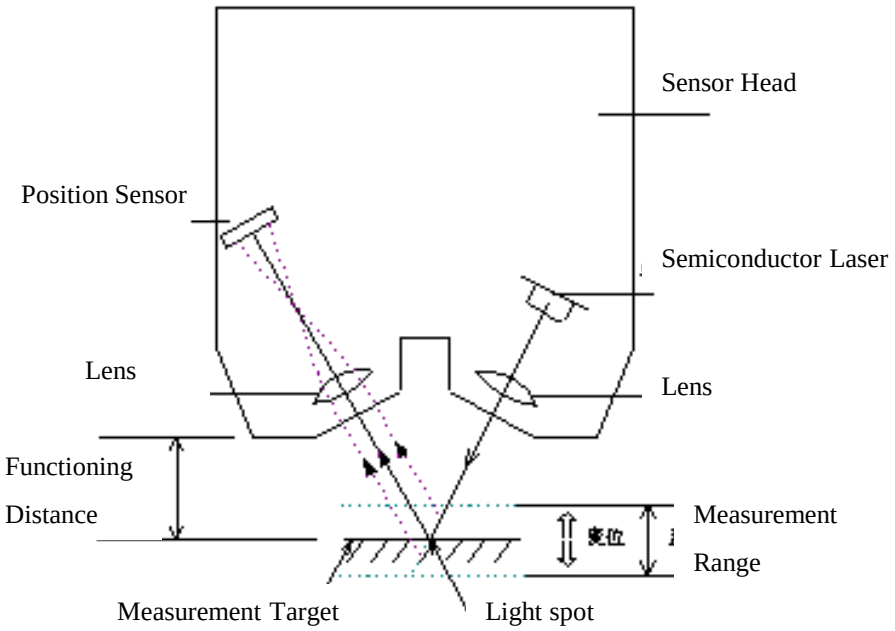


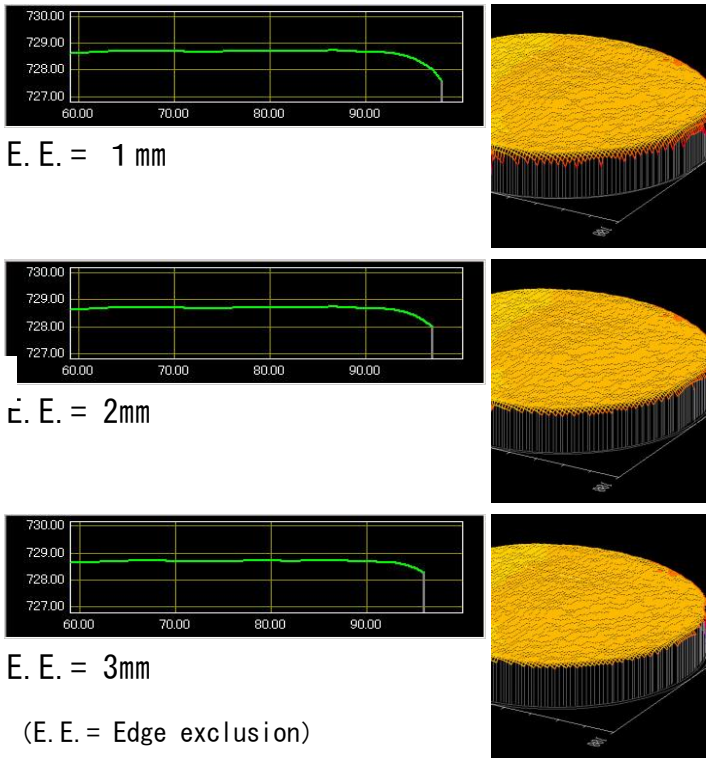
Stable Transfer System



Edge Exclusion Min.1mm

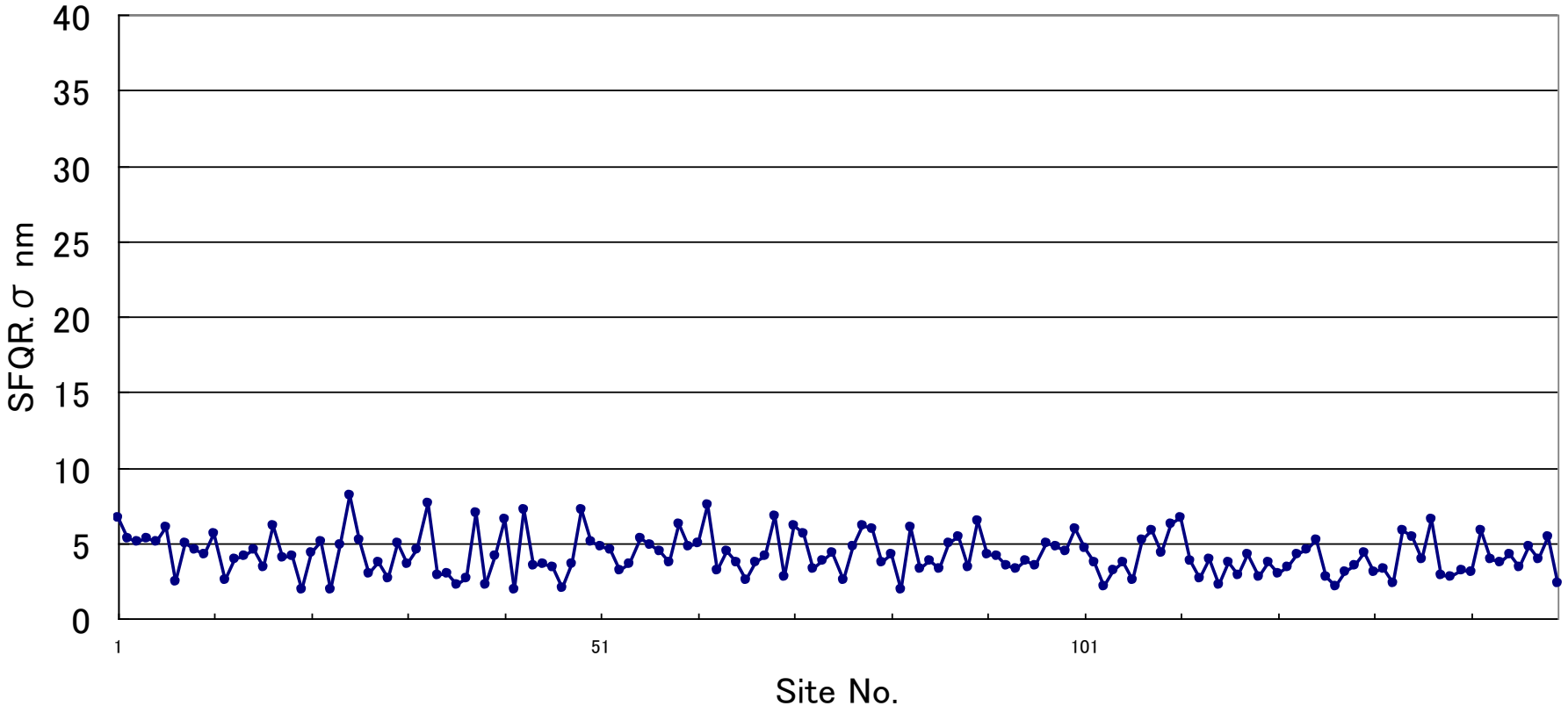
Small spot diameter for Laser displacement sensor





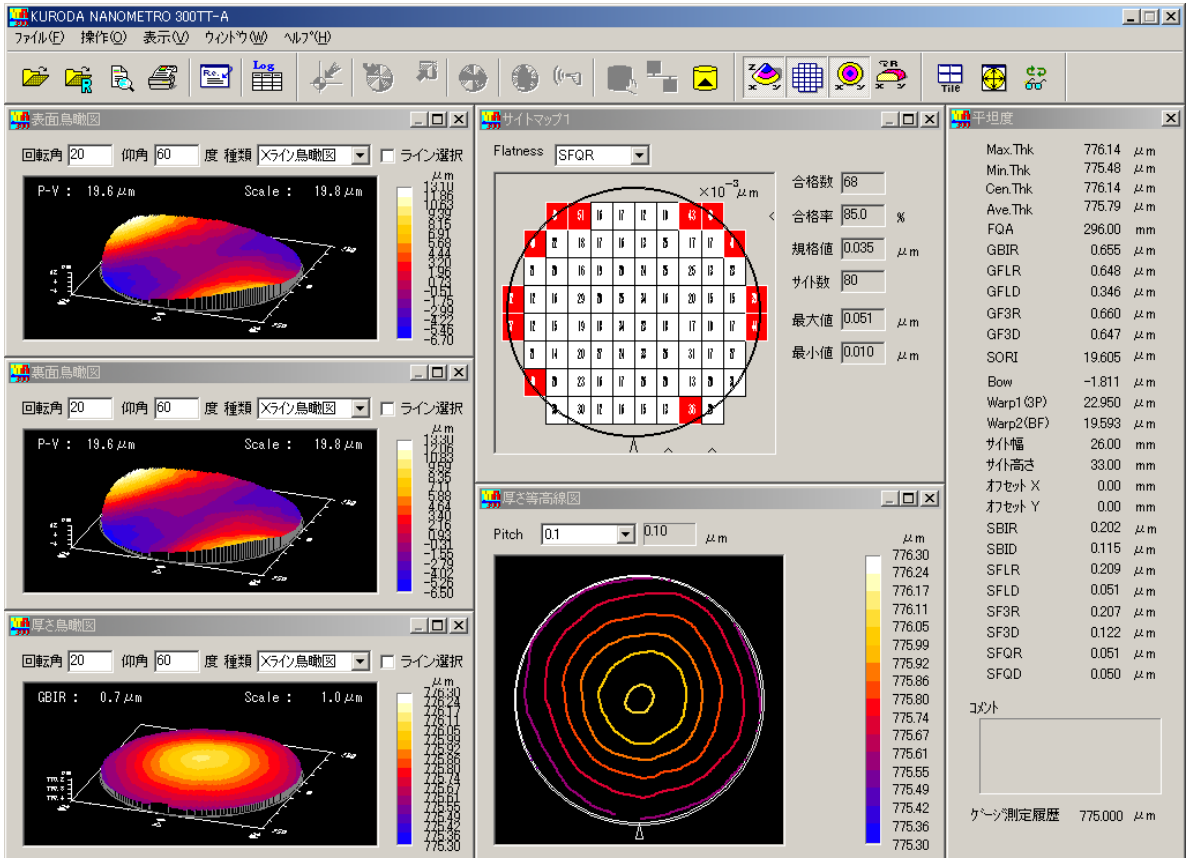
Repeatability 15nm(σ)

Repeatability, 10Times, KKS300Wafer
SFQR, SiteSize26x8, EE3



KURODA

Example of Flatness Measurement

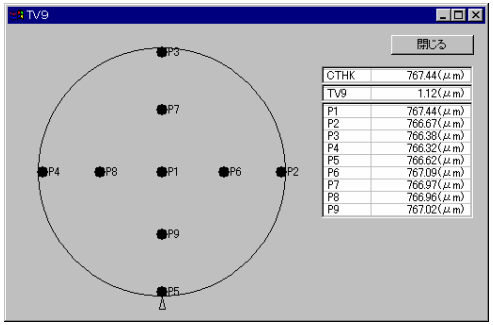


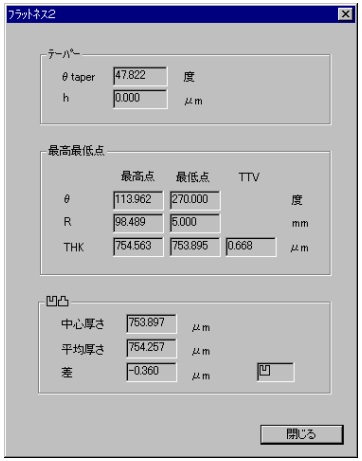
Flatness & Shape Measurement

(Flatness&Shape)

Measurement parameter conforms to SEMI Standard

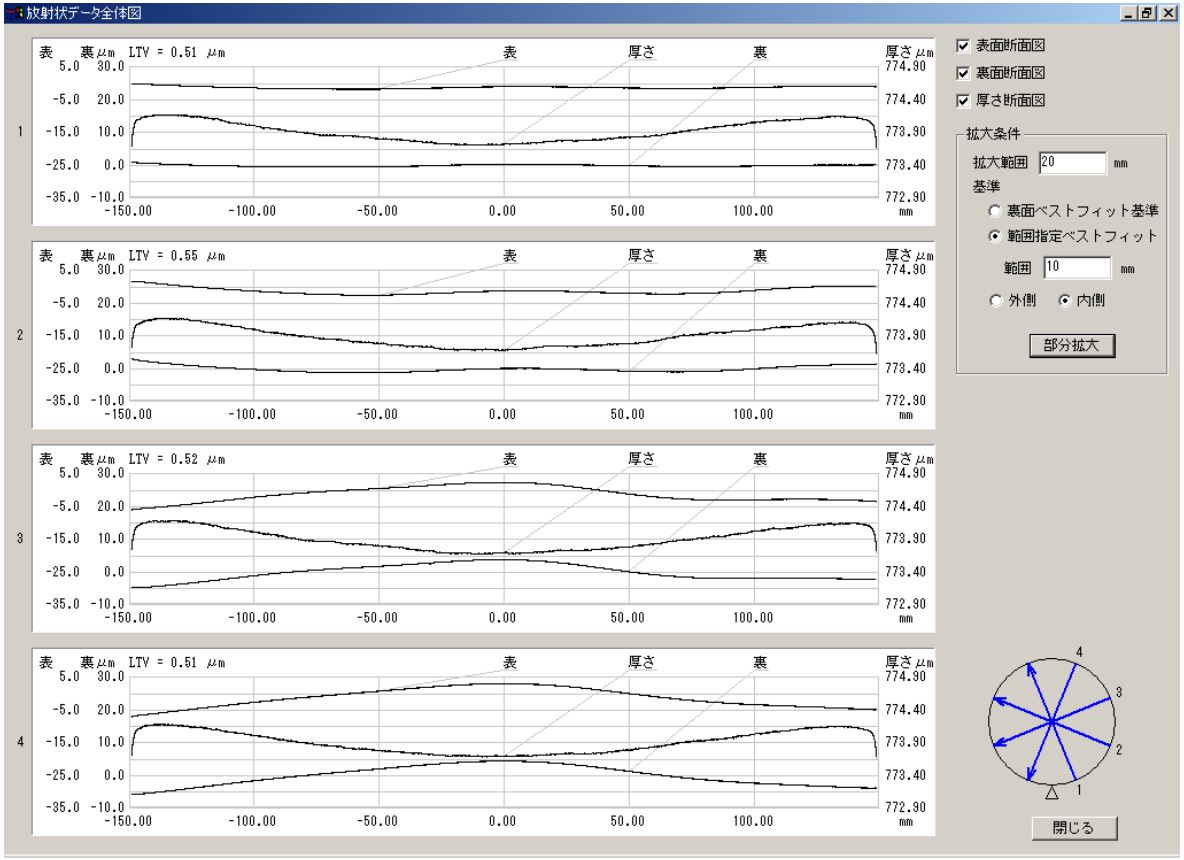
- Max.Thk, Min.Thk, Cen.Thk, Ave.Thk,
- GBIR(TTV), GFLR(TIR), GFLD(FPD), GF3R, GF3D,
- SORI,Bow,Warp-3P,Warp-BF,
- SBIR(LTV),SBID(SFPD),SFLR,SF3R,SF3D, SFQR(STIR),SFQD





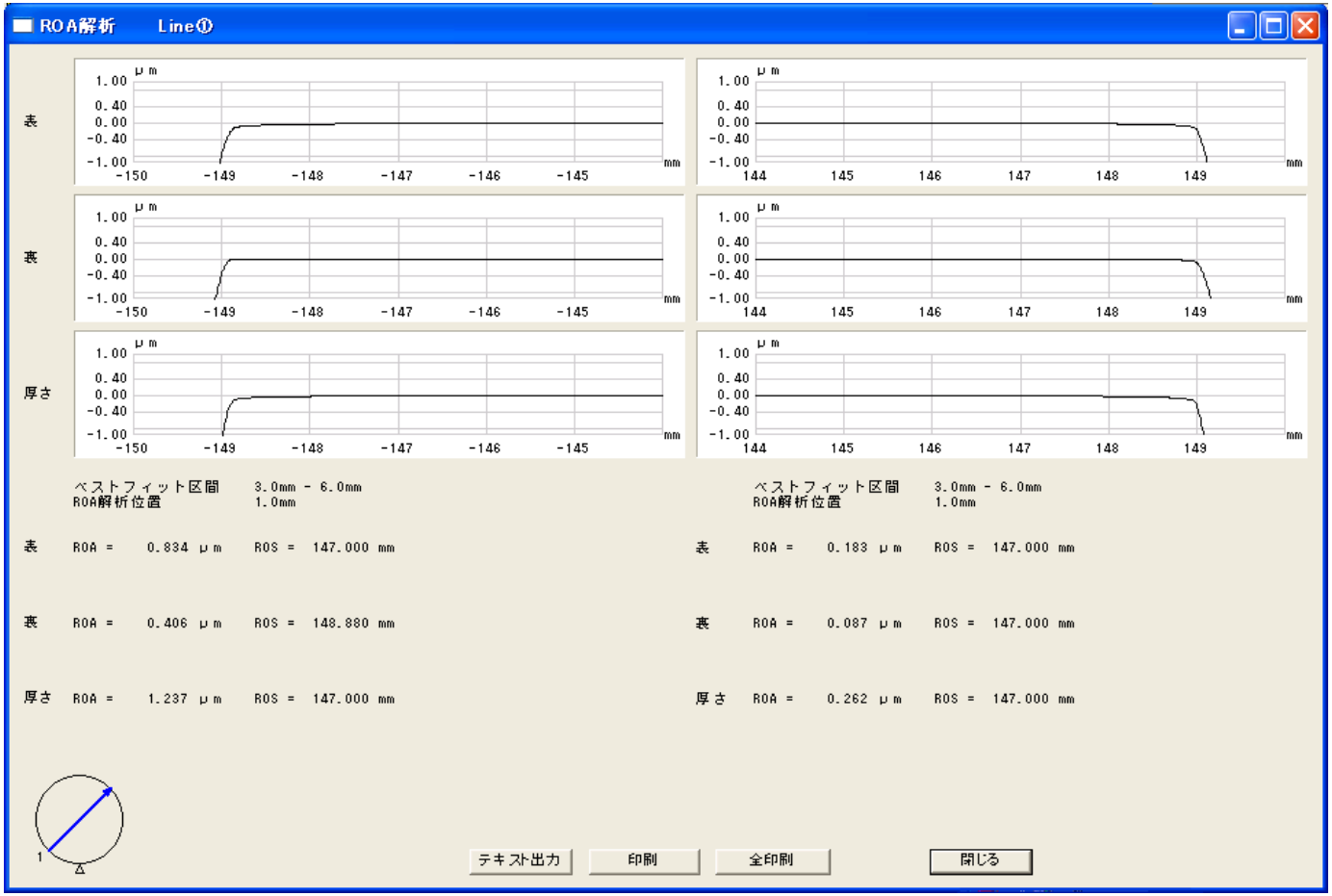
KURODA

Example of Radial Measurement



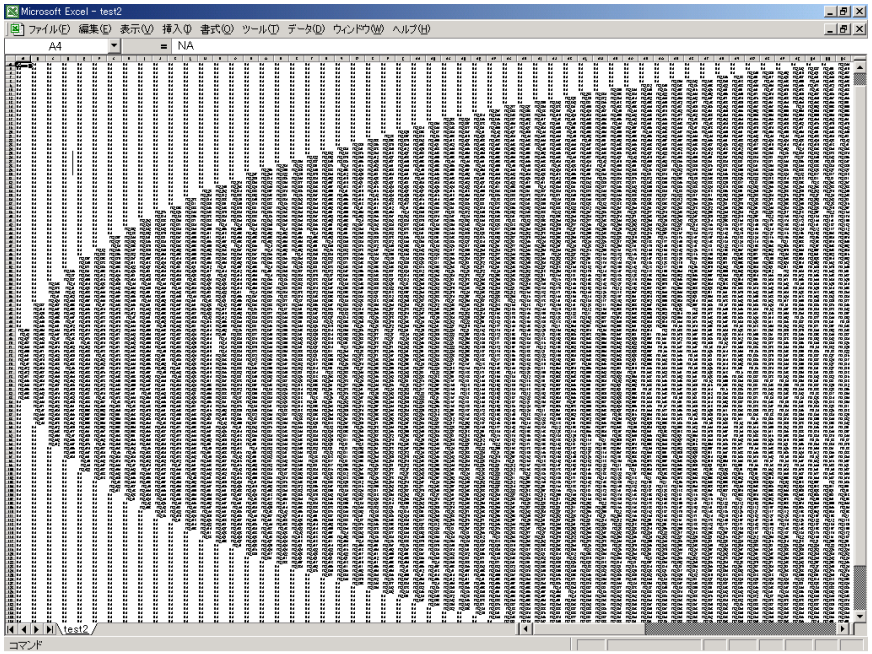
KURODA

Example of Edge Roll-off



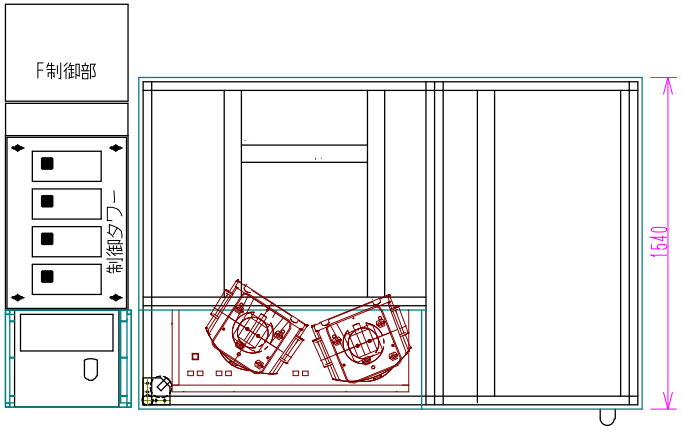
CSV out-put of lattice data

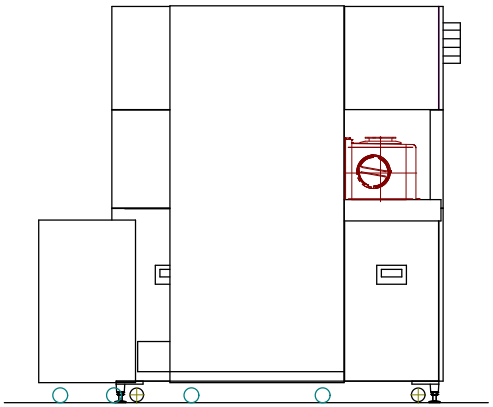
Raw thickness data can be out-put as CSV format

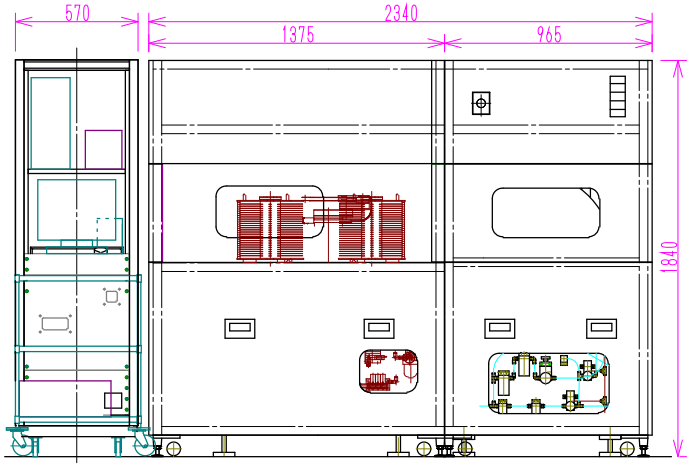


KURODA

Drawing for Open cassette Spec.







Drawing for FOUP spec.